SDLS118 – DECEMBER 1983 – REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

The '73, and 'H73, contain two independent J-K flip-flops with individual J-K, clock, and direct clear inputs. The '73, and 'H73, are positive pulse-triggered flip-flops. J-K input is loaded into the master while the clock is high and transferred to the slave on the high-to-low transition. For these devices the J and K inputs must be stable while the clock is high.

The 'LS73A contains two independent negativeedge-triggered flip-flops. The J and K inputs must be stable one setup time prior to the highto-low clock transition for predictable operation. When the clear is low, it overrides the clock and data inputs forcing the Q output low and the \overline{Q} output high.

The SN5473, SN54H73, and the SN54LS73A are characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN7473, and the SN74LS73A are characterized for operation from 0 °C to 70 °C.

SN5473, SN54LS73A . . . J OR W PACKAGE SN7473 . . . N PACKAGE SN74LS73A . . . D OR N PACKAGE

(TOP VIEW)

	13] 10
1K 🖾 3	12 10
Vcc□₄	
2CLK	10]] 2K
	9 ¹ 20
2J 🗗 7	8 20

73	
FUNCTION	TABLE

	INPUT	s		OUTPUTS				
CLR	CLK	J	К	٥	ā			
L	X	Х	X	L	н			
н	л	L	L	00	αo			
н	л	н	L	н	L			
н	л	L	н	L	н			
н	л	н	н	TOG	GLE			

'LS73A FUNCTION TABLE

INPUT	rs		OUTP	UTS
CLK	J	к	٩	ā
х	Х	Х	L	н
Ļ	L	L	ao	$\overline{\alpha}_{O}$
Ļ	н	L	н	L
1	L	н	L	н
1	н	н	TOG	GLE
н	х	x	ao	āo
	CLK X ↓ ↓	X X ↓ L ↓ H ↓ L ↓ H	CLK J K X X X ↓ L L ↓ H L ↓ H L ↓ H H ↓ H H	CLK J K Q X X X L ↓ L L QO ↓ H L H ↓ L H L ↓ H H TOG

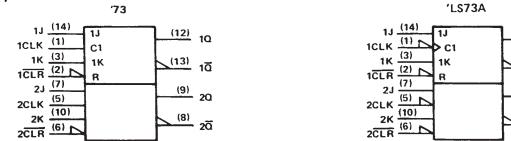
FOR CHIP CARRIER INFORMATION. CONTACT THE FACTORY

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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logic symbols[†]



(12) 10

<u>(13)</u> 10

20

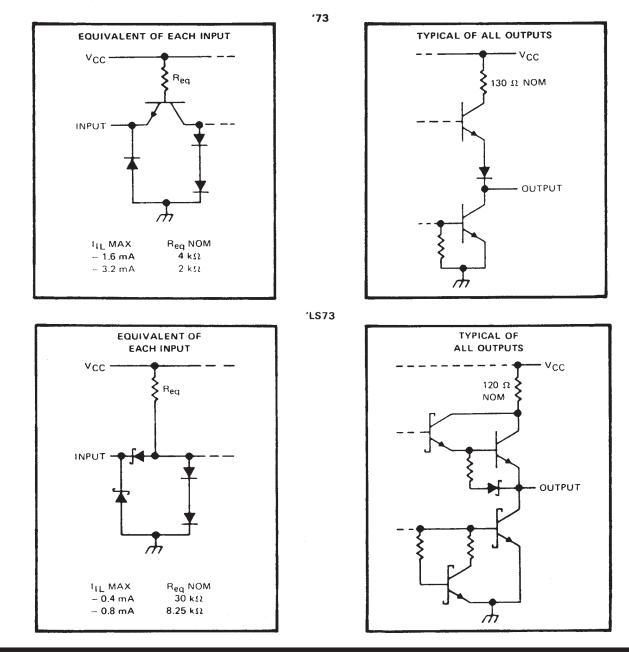
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(9)

(8)

[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

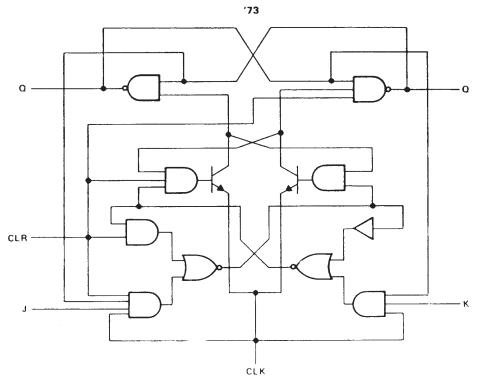
schematics of inputs and outputs



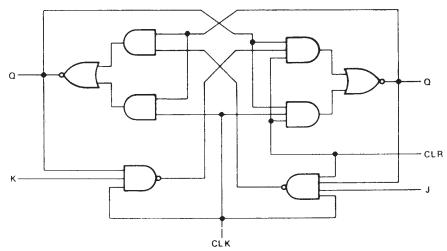


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logic diagrams (positive logic)







absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, Vcc (See Note 1)	
Input voltage: '73	5.5 V
1S73A	7 V
	SN54' 55°C to 125°C
	SN74' 0° C to 70°C
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.



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recommended operating conditions

				SN547	3		SN747	3	4 45 14 7
			MIN	NOM	MAX	MIN NOM MAX		UNIT	
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage			-	0.8			0.8	V
ЮН	High-level output current			- 0.4			- 0.4	mA	
IOL	Low-level output current	· · · · · · · · · · · · · · · · · · ·			16			16	mA
		CLK high	20			20	-		
tw	Pulse duration	CLK low	47			47			ns
		CLR low	25			25			
t _{su}	Input setup time before CLK †		0			0			ns
th	Input hold time data after CLK↓	0		_	0			ns	
TA	Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			EST CONDITION	int		SN5473			SN7473		UNIT
PAP	RAMETER	1	EST CONDITION	19,	MIN	TYP‡	MAX	MIN	TYP\$	MAX	
VIK		V _{CC} = MIN,	l _l = 12 mA				- 1.5			- 1.5	V
VOH		V _{CC} = MIN, I _{OH} = - 0.4 mA	V _{IH} = 2 V,	V _{IL} = 0.8 V,	2.4	3.4		2.4	3.4		v
VOL		V _{CC} = MIN, I _{OL} = 16 mA	V _{IH} = 2 V,	V _{IL} ≈ 0.8 V,		0.2	0.4		0.2	0.4	v
4		V _{CC} = MAX,	V _I = 5.5 V				1			1	mA
Чн	J or K CLR or CLK	V _{CC} = MAX,	V ₁ = 2.4 V				40 80			40 80	μA
	J or K						- 1.6			- 1.6	
1 _{1L}	CLR	V _{CC} = MAX,	V ₁ = 0.4 V				- 3,2			- 3.2] mA
	CLK		·				- 3.2			- 3.2]
los§		V _{CC} = MAX			- 20		- 57	- 18		- 57	mA
Icc1		V _{CC} = MAX,	See Note 2			10	20	<u> </u>	10	20	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 V$, $T_A = 25 °C$.

§ Not more than one output should be shorted at a time.

[¶] Average per flip-flop.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and \overline{Q} outputs high in turn. At the time of measurement, the clock input is grounded.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 3)

PARAMETER#	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	түр	MAX	UNIT
f _{max}				15	20		MHz
^t PLH	CLR	ā.			16	25	ns
^t PHL	CLN	٩	$R_{L} = 400 \Omega$, $C_{L} = 15 pF$		25	40	ns
^t PLH	CLK	$Q \text{ or } \overline{Q}$			16	25	ns
^t PHL	ULK	2012			25	40	ns

#fmax = maximum clock frequency: tpLH = propagation delay time, low-to-high-level output; tpHL = propagation delay time, high-tolow-level output.

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



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recommended operating conditions

			S	N54LS7	3A	St	174LS7	3A	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	V.
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			0.8	V
юн	High-level output current	ligh-level output current						- 0.4	mA
IOL	Low-level output current			4			8	mA	
fclock	Clock frequency		0		30	0		30	MHz
•	Pulse duration	CLK high	20			20			
t _w	Fulse duration	CLR low	25			20			ាទ
		data high or low	20			20			
t _{su}	Set up time-before CLK4	CLR inactive	20			20			ns
t _h	Hold time-data after CLK I	0			0			ns	
TA	Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DAMETED		EST CONDITION	et.	SI	154LS7	BA	SI	174LS7	3A	UNIT	
PA	RAMETER		STCONDITION	3'	MIN	TYP#	MAX	MIN	TYP‡	MAX	UNIT	
VIK		V _{CC} = MIN,	t ₁ = - 18 mA				- 1.5			- 1.5	V	
v _{он}		V _{CC} = MIN, I _{OH} = – 0.4 mA	V _{IH} = 2 V,	V _{IL} = MAX,	2.5	3.4		2.7	3.4		v	
VOL		V _{CC} = MIN, I _{OL} = 4 mA	V _{IL} = MAX,	V _{IH} = 2 V,		0.25	0.4		0.25	0.4	v	
		V _{CC} = MIN, I _{OL} = 8 mA	V _{IL} = MAX,	V _{1H} = 2 V,					0.35	0.5		
	J or K						0.1			0.1		
4	CLR	V _{CC} = MAX,	MAX, VI = 7 V				0.3			0.3	mA	
	CLK					0.4			0.4			
	J or K						20			20		
ЧН	CLR	V _{CC} = MAX,	V _I = 2.7 V				60			60	μA	
	CLK						80			80		
	J or K		<u> </u>				0.4			- 0,4	mA	
ΠL	CLR or CLK	V _{CC} = MAX,	V ₁ = 0.4 V		- 0.8			- 0.8				
los		V _{CC} = MAX,	See Note 4		- 20		- 100	- 20		- 100	mA	
ICC (T	otal)	V _{CC} = MAX,	See Note 2		1	4	6		4	6	mA	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and \overline{Q} outputs high in turn. At the time of measurement, the clock input is grounded,

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V_O = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	түр	MAX	UNIT
f _{max}				30	45		MHz
^t PLH	CLR or CLK	Q or Q	$R_L = 2 k\Omega$, $C_L = 15 pF$		15	20	ns
^t PHL	CLH OF CLK	Q or Q	-		15	20	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9675101QCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9675101QC A SNJ54LS73AJ	Samples
5962-9675101QDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9675101QD A SNJ54LS73AW	Samples
5962-9675101QDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9675101QD A SNJ54LS73AW	Samples
SN54LS73AJ	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS73AJ	Samples
SN54LS73AJ	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS73AJ	Samples
SN74LS73AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS73A	Samples
SN74LS73AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS73A	Samples
SN74LS73ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS73A	Samples
SN74LS73ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS73A	Samples
SN74LS73AN	ACTIVE	PDIP	Ν	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS73AN	Samples
SN74LS73AN	ACTIVE	PDIP	Ν	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS73AN	Samples
SN74LS73ANE4	ACTIVE	PDIP	Ν	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS73AN	Samples
SN74LS73ANE4	ACTIVE	PDIP	Ν	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS73AN	Samples
SNJ54LS73AJ	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9675101QC A SNJ54LS73AJ	Samples
SNJ54LS73AJ	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9675101QC A SNJ54LS73AJ	Samples
SNJ54LS73AW	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9675101QD A	Samples



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
										SNJ54LS73AW	
SNJ54LS73AW	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9675101QD A SNJ54LS73AW	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS73A, SN74LS73A :



• Catalog : SN74LS73A

Military : SN54LS73A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

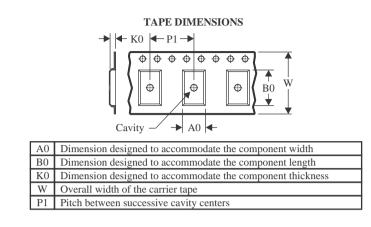


Texas

NSTRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



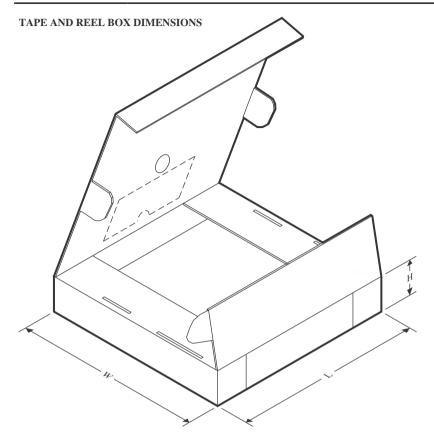
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS73ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



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PACKAGE MATERIALS INFORMATION

1-Jul-2023



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS73ADR	SOIC	D	14	2500	356.0	356.0	35.0

TEXAS INSTRUMENTS

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TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
5962-9675101QDA	W	CFP	14	1	506.98	26.16	6220	NA
SN74LS73AD	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS73AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS73AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS73ANE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS73ANE4	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS73AW	W	CFP	14	1	506.98	26.16	6220	NA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



J0014A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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